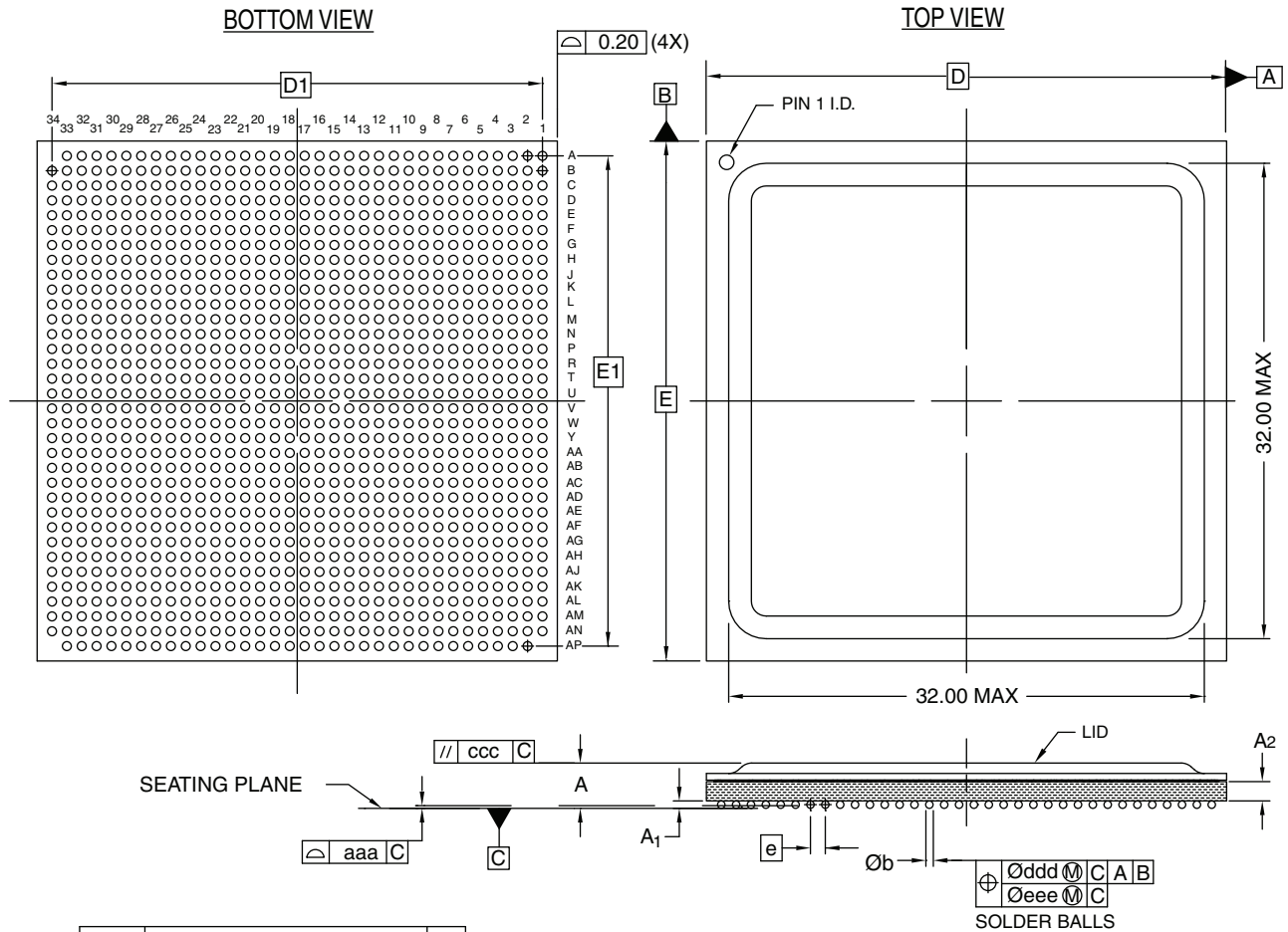


# Flip-Chip BGA (FF1153) Package



SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	2.70	<i>~</i>	3.40	
A <sub>1</sub>	0.40	0.50	0.60	
A <sub>2</sub>	1.00	1.10	1.20	
D/E	35.00 BASIC			
D <sub>1</sub> /E <sub>1</sub>	33.00 REF			
e	1.00 BASIC			
Øb	0.50	0.60	0.70	
aaa	<i>~</i>	<i>~</i>	0.20	
ccc	<i>~</i>	<i>~</i>	0.35	
ddd	<i>~</i>	<i>~</i>	0.30	
eee	<i>~</i>	<i>~</i>	0.10	
M	34			2

### NOTES:

- ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
- SYMBOL 'M' IS THE BALL MATRIX SIZE.
- CONFORMS TO JEDEC MS-034-AAR-1 (DEPOPULATED)

## 1153-BALL FLIP CHIP BGA (FF1153/FFG1153)

## Revision History

The following table shows the revision history for this document.

Date	Version	Revision
05/15/06	1.0	Initial Xilinx release.
12/15/08	1.1	Corrected symbol A2 dimension.